

Material Composition Data



Product: MS3V-T

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MS3V-T - SM Crystal

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Cap	Brass (Cu58Zn39Pb3)	Brass	12597-71-6	40.400	100.00
Cap gold flash	Gold flashed (0.1 micron)	Au	7440-57-5	0.100	100.00
Electrodes	Chromium	Cr	7440-47-3	0.001	10.00
	Gold	Au	7440-57-5	0.009	90.00
Epoxy adhesive	Epoxy powder	Epoxy	129915-35-1	0.023	30.26
	Silver	Ag	7440-22-4	0.053	69.74
Holder ring	Alloy 42	Fe	7439-89-6	1.026	57.00
	Alloy 42	Mn	7439-96-5	0.018	1.00
	Alloy 42	Ni	7440-02-0	0.756	42.00
Lead plating	Copper base (1-3 micron)	Cu	7440-50-8	1.100	99.01
	Solder Pb93/Sn7 (7-11	Pb	7439-92-1	0.010	0.90
	Solder Pb93/Sn7 (7-11	Sn	7440-31-5	0.001	0.09
Leads	Kovar	Co	7440-48-4	0.180	18.00
	Kovar	Fe	7439-89-6	0.530	53.00
	Kovar	Ni	7440-02-0	0.290	29.00
Resonator	Quartz	SiO ₂	14808-60-7	0.650	100.00
Seal	Glass	SiO ₂	14808-60-7	2.700	100.00
Total Mass:				47.847 mg	

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